Code No: B5506, B5703

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## JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY HYDERABAD M.Tech II Semester Examinations, October/November 2011 LOW POWER VLSI DESIGN

## (COMMON TO EMBEDDED SYSTEMS, VLSI SYSTEM DESIGN)

Time: 3hours Max. Marks: 60

## Answer any five questions All questions carry equal marks

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- 1.a) What are the difference problems associated with Low Power VLSI Design? Discuss.
  - b) Explain about SOI Technology.

[12]

- 2.a) Draw the structure for optimized twin Well BI CMOS structure with self aligned p and  $n^+$  buried layers for improved packing density and explain about the same.
  - b) Explain about punch through in short channel MUSFETS.

[12]

- 3.a) With the help of neat sketches explain about Polysizicon Emitter Highperformance BICMOS structures and explain about the process steps.
  - b) What are the steps in implementing copper metallization in deep sub micros process? Explain. [12]
- 4.a) Give the 0.2  $\mu$  in SOI BICMOS process flow with sketches and explain the same.
  - b) Using necessary equations, explain about the properties of fully depleted SOI MOSFETS. [12]
- 5.a) Explain about MOS structure capacitances, using necessary equations.
  - b) Explain about LEVEL 3 Model MOSFETS.

[12]

- 6.a) Explain about EKV MOSFET model with the help of a circuit diagram.
  - b) Explain the sub micron CMOS Technology.

[12]

- 7.a) Draw the circuit for FS–CMBL two in put NAND gate with positive feedback and explain the same.
  - b) Draw a logic circuit in BICMOS configuration using lateral parasitic pnp BJT in a PMOS. Structure BIFET and explain its working. [12]
- 8. Write notes on any Two
  - a) ESD free BICMOS circuits
  - b) Full Swing Multi Drain / Multi Collector complimentary BICMOS buffers
  - c) Gummel Poon Model of MOSFETS.

[12]

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